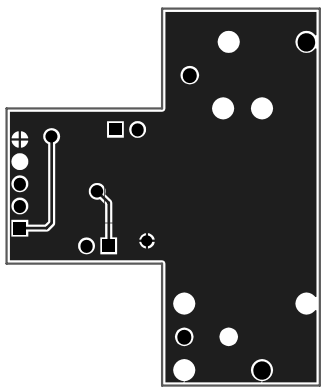
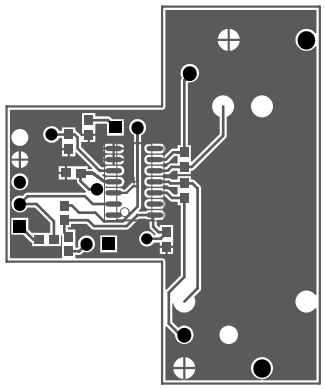
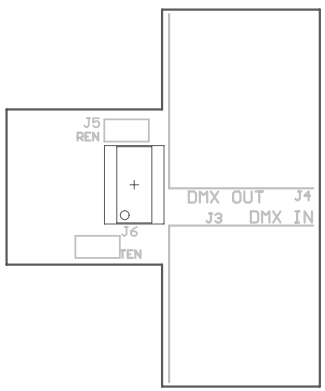
TOP COPPER (.GTL)



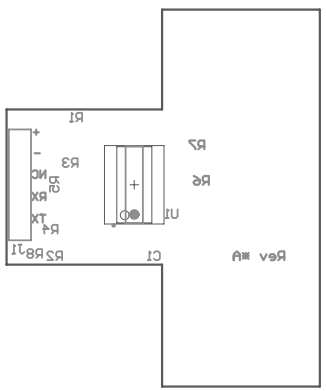
BOTTOM COPPER (.GBL)

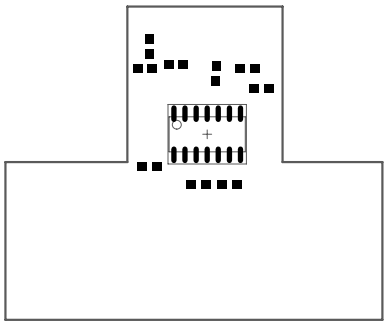


TOP OVERLAY (.GTO)

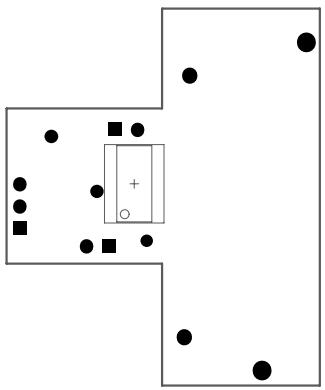


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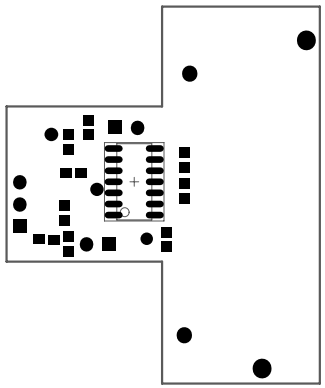


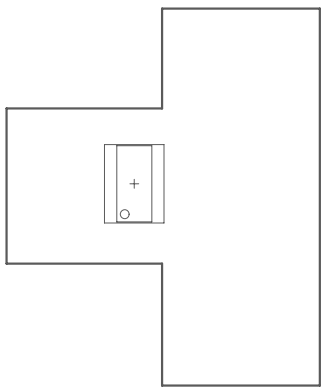


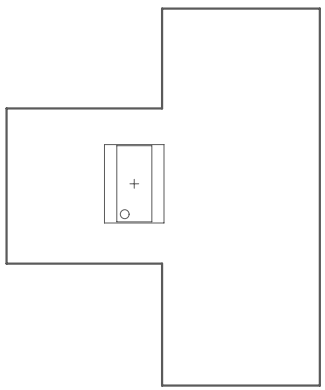
TOP SOLDERMASK (.GTS)

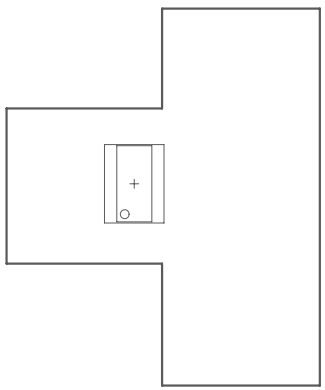


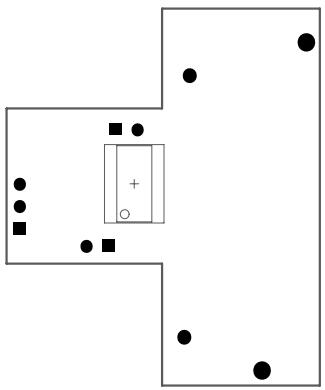
BOTTOM SOLDERMASK (.GBS)

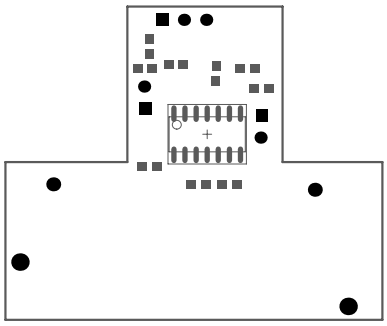


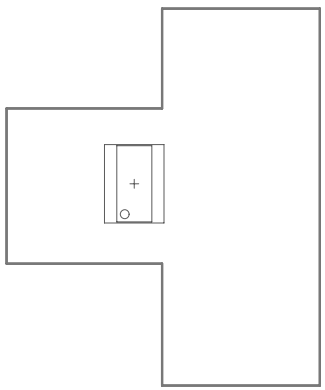










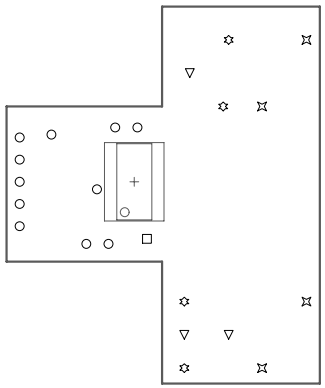


Symbol	Hit Count	Tool Size	Plated	Hole Type
□	1	28mil (0.7112mm)	PTH	Round
○	11	37mil (0.9398mm)	PTH	Round
▽	3	47.244mil (1.2mm)	PTH	Round
☼	4	62.992mil (1.6mm)	PTH	Round
⌑	4	62.992mil (1.6mm)	NPTH	Round
	23 Total			

NOTES:

1. MATERIAL: 2 LAYERS, FR4, 0.062 +/-10% IN. THK.
2. COPPER 0.001 AVERAGE THICKNESS.
3. SOLDERMASK: TWO SIDES, LPI.
4. HOLE SIZES: FINISHED SIZES LISTED.
5. MINIMUM SPACE .010'', MINIMUM TRACE .010''.
6. SILKSCREEN: 2 Layer (Top and Bottom)
7. Use 1oz copper

DRILL AND TRIM(.GD1)



DIMs AS NOTED

Cypress Semiconductor

ENGR: UKK/BTK
(408)-432-7058

CAD: UKK/PUP/BTK
(408)-432-7058

TITLE: RS485 Bridge

PART NO.:

REV: *A

DATE: 3 NOV 2008

CYPRESS SEMICONDUCTOR
198 Champion Ct
San Jose CA 95134
USA

MATERIAL — SEE NOTES —

FILE NAME: RS485_Adapter.PcbDoc

LAYER:

GERBER:

